


PRODUCT / PROCESS CHANGE INFORMATION

1. PCI basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCI No.	AMS/23/14198	
1.3 Title of PCI	Wire Bonding improvement on Cu wire/NiPdAu Leadframe for SOT23H and SC70H Voltage Regulators & References	
1.4 Product Category	See product list	
1.5 Issue date	2023-06-29	

2. PCI Team

2.1 Contact supplier	
2.1.1 Name	KRAUSE INA
2.1.2 Phone	+49 89460062370
2.1.3 Email	ina.krause@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Marcello SAN BIAGIO
2.1.2 Marketing Manager	Salvatore DI VINCENZO
2.1.3 Quality Manager	Giuseppe LISI

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Methods	Change in process technique for die preparation/cleaning	Carsem Malaysia

4. Description of change

	Old	New
4.1 Description	Standard bonding on the ground bond for the SOT23H and SC70H	BSOB bonding on the ground bond for the SOT23H and SC70H
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	No impact	

5. Reason / motivation for change

5.1 Motivation	Strengthening of ground bonding on NiPdAu lead frame of the current copper wire ST devices in SOT23H and SC70H
5.2 Customer Benefit	QUALITY IMPROVEMENT

6. Marking of parts / traceability of change

6.1 Description	Assembly code in marking
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7. Timing / schedule

7.1 Date of qualification results	2023-06-22
7.2 Intended start of delivery	2023-07-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

14198 Public product.pdf

10. Affected parts		
10.1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	LDK120C33R	
	LDK120DM33R	
	LDK120M-R	

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